

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSC016N03LS G	**Issued**	04. April 2021
MA#	MA001623868		
Package	PG-TDSON-8-1	**Weight***	121.96 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.071	3.34	3.34	33382	33382
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		93	
	non noble metal	iron	7439-89-6	0.038	0.03		310	
	non noble metal	copper	7440-50-8	37.762	30.94	30.98	309625	310028
wire	non noble metal	copper	7440-50-8	0.031	0.03	0.03	255	255
encapsulation	organic material	carbon black	1333-86-4	0.080	0.07		659	
	plastics	epoxy resin	-	5.709	4.68		46807	
	inorganic material	silicondioxide	60676-86-0	34.412	28.22	32.97	282162	329628
leadfinish	non noble metal	tin	7440-31-5	1.452	1.19	1.19	11903	11903
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1357	1357
solder	non noble metal	tin	7440-31-5	0.066	0.05		538	
	noble metal	silver	7440-22-4	0.082	0.07		673	
	non noble metal	lead	7439-92-1	3.135	2.57	2.69	25707	26918
heatspreader	inorganic material	phosphorus	7723-14-0	0.003			28	
	non noble metal	iron	7439-89-6	0.011	0.01		93	
	non noble metal	copper	7440-50-8	11.320	9.28	9.29	92818	92939
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.007	0.01		55	
	non noble metal	iron	7439-89-6	0.022	0.02		183	
	noble metal	silver	7440-22-4	1.289	1.06		10573	
	non noble metal	copper	7440-50-8	22.292	18.28	19.37	182779	193590
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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